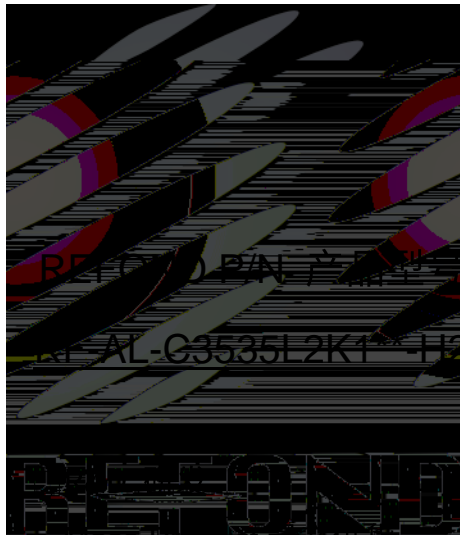


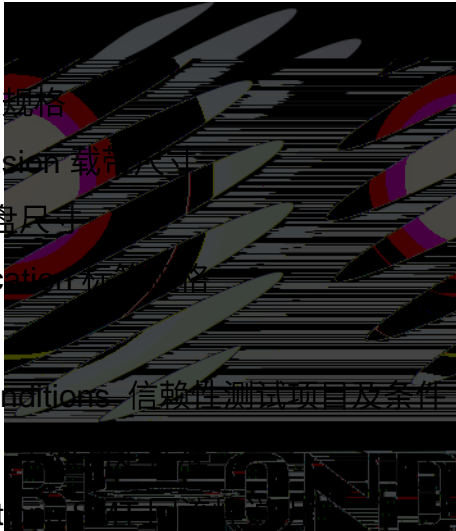
SPECIFICATION 产品规格书

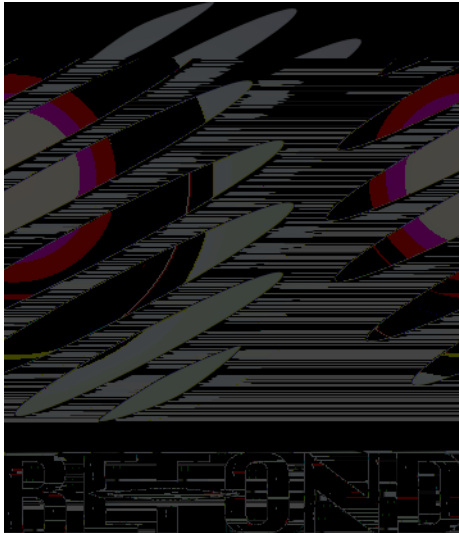


Mass Product 量产供货

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1.4 Package Dimension 封装尺寸

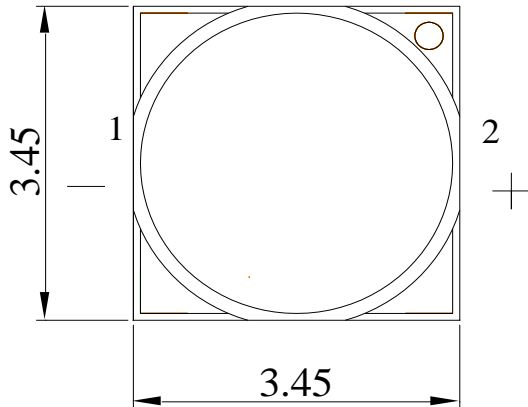


Fig.1-1 Top view 正面视图

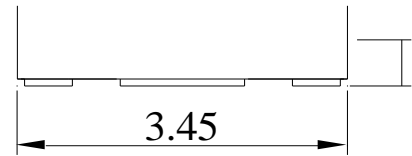


Fig.1-2 Side view

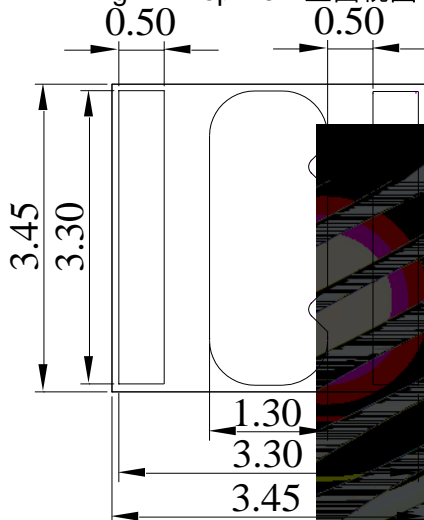


Fig.1-3 Bottom view

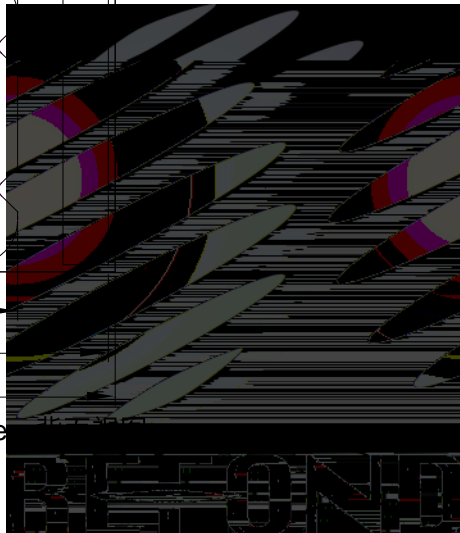


Fig.1-4 Polarity 极性

Fig.1-5 Soldering patterns 推荐焊盘

Notes 备注:

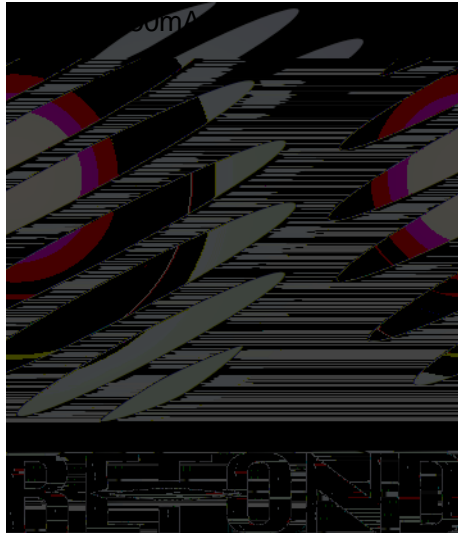
1. All dimensions units are millimeters. 所有尺寸标注单位为毫米
2. All dimensions tolerances are $\pm 0.2\text{mm}$ unless otherwise noted. 除特别标注外, 所有尺寸公差为 ± 0.2 毫米

1.5 Product Parameters 产品参数

Table 1-1 Electrical / Optical Characteristics at Ts=25°C 电性与光学特性

Item 项目	Symbol 符号	Test Condition 测试条件	Value		
			Min. (最小值)	Typ (典型值)	Max. (最大值)
Forward Voltage (正向电压)	V_F	$I_F=350\text{mA}$	2.6	---	3.4
RF-AL-C3535L2K127-H2 Luminous Flux (光通量)	I_V	$I_F=350\text{mA}$	140	---	170
		$I_F=700\text{mA}$	260	---	320
RF-AL-C3535L2K130-H2 Luminous Flux (光通量)	I_V	$I_F=350\text{mA}$	150	---	180
		$I_F=700\text{mA}$	280	---	340
RF-AL-C3535L2K135-H2 Luminous Flux (光通量)	I_V	$I_F=350\text{mA}$	---	---	190

lm



RF-AL-C3535L2K145-H2 Correlated Color Temperature 色温	CCT	$I_F=350\text{mA}$	---	4500	---	K
RF-AL-C3535L2K150-H2 Correlated Color Temperature 色温	CCT	$I_F=350\text{mA}$	---	5000	---	K
RF-AL-C3535L2K157-H2 Correlated Color Temperature 色温	CCT	$I_F=350\text{mA}$	---	5700	---	K
RF-AL-C3535L2K160-H2 Correlated Color Temperature 色温	CCT	$I_F=350\text{mA}$	---	6000	---	K
RF-AL-C3535L2K1**-H2 Color Rendering Index (显色指数)	Ra	$I_F=350\text{mA}$	80	---	---	---
Reverse Current (漏电流)	I_R	$V_R=5\text{V}$	---	---	10	μA
Viewing Angle (发光角度)				120	---	deg
Thermal Resistance. (热阻)	R_{THJ-S}			1.90	---	$^{\circ}\text{C}/\text{W}$

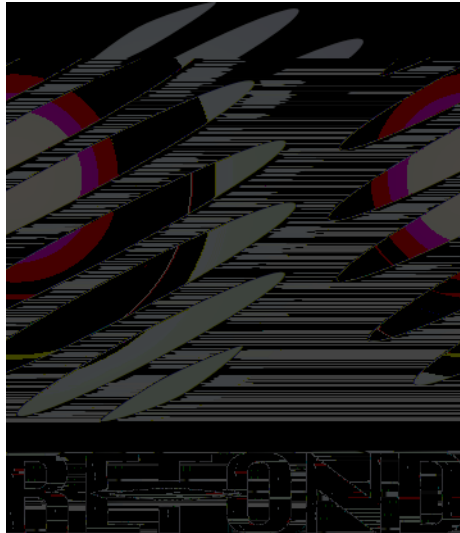
 Table 1-2 Absolute Maximum Ratings at $T_s=25^{\circ}\text{C}$ 绝对最大值

Parameter (参数)	Symbol (符号)	Rating (值)	Units (单位)
Power Dissipation (功耗)		6800	mW
Forward Current (正向电流)	I_F	2000	mA
Peak Forward Current (峰值电流)	I_{FP}	3000	mA
Reverse Voltage (反向电压)	V_R	5	V

Notes 备注:

1. 1/10 Duty cycle, 0.1ms pulse width. 脉宽0.1ms,占空比1/10.

2. The above forward voltage measurement allowance tolera4(ar36351 g0.251 G[P1s)Pd262 2)0 G73/Span #MCID 7/La



1.5.1 Bin Range Of Forward Voltage and Luminous Intensity (IF=350mA)电压与光强分 BIN 范围(IF=350mA)

Table 1-3

V_F V	F0	G0
---------	----	----

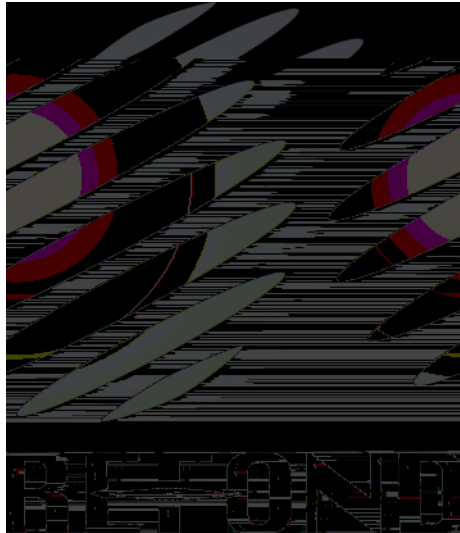
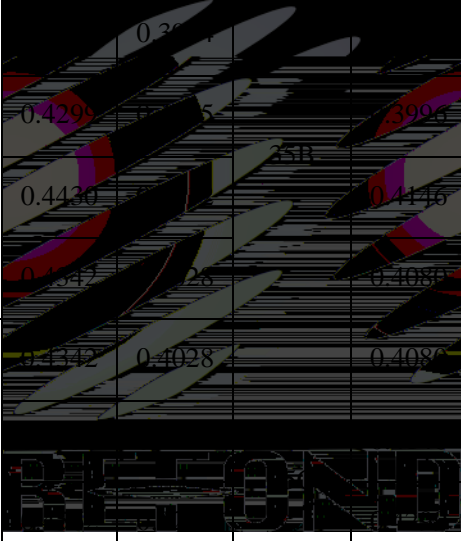
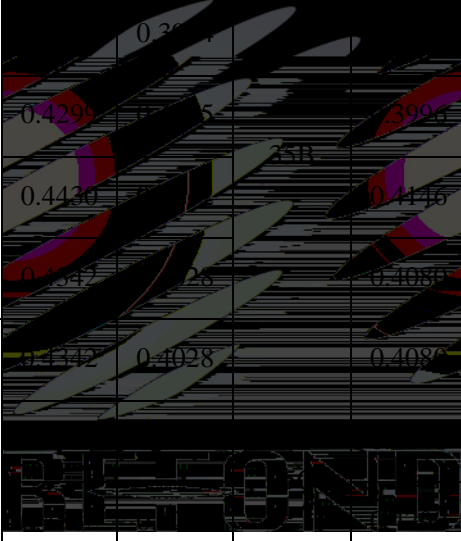


Table 1-4 Chromaticity Region & Coordinates

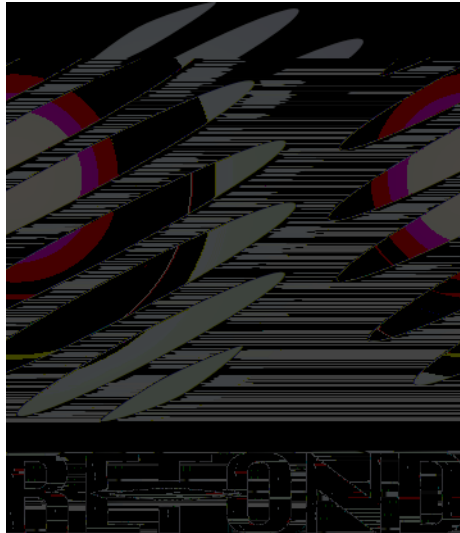
	CIE-X	CIE-Y	Region	CIE-X	CIE-Y	Region	CIE-X	CIE-Y	Region	CIE-X	CIE-Y
2700K			3000K			3500K			4000K		
27A	0.4373	0.3893	30A	0.4147	0.3814	35A	0.3889	0.3690	40A	0.3670	0.3578
	0.4465	0.4071		0.4221	0.3984		0.3941	0.3848		0.3702	0.3722
	0.4582	0.4099		0.4342	0.4028		0.4080	0.3916		0.3825	0.3798
	0.4483	0.3919		0.4259	0.3853		0.4017	0.3751		0.3783	0.3646
27B	0.4465	0.4071	30B				0.3848	40B	0.3702	0.3722	
	0.4562	0.4260					0.4015		0.3736	0.3874	
	0.4687	0.4289					0.4089		0.3869	0.3958	
	0.4582	0.4099					0.3916		0.3825	0.3798	
27C	0.4582	0.4099	30C				0.3916	40C	0.3825	0.3798	
	0.4687	0.4289					0.4089		0.3869	0.3958	
	0.4813	0.4319					0.4165		0.4006	0.4044	
	0.4700	0.4126					0.4465		0.4071	0.4221	0.3984
27D	0.4483	0.3919	30D	0.4259	0.3853	35D	0.4017	0.3751	40D	0.3783	0.3646
	0.4582	0.4099		0.4342	0.4028		0.4080	0.3916		0.3825	0.3798
	0.4700	0.4126		0.4465	0.4071		0.4221	0.3984		0.3950	0.3875
	0.4593	0.3944		0.4373	0.3893		0.4147	0.3814		0.3898	0.3716
Region	CIE-X	CIE-Y	Region	CIE-X	CIE-Y	Region	CIE-X	CIE-Y	Region	CIE-X	CIE-Y
4500K			5000K			5700K			6500K		

45A	0.3530	0.3597	50A	0.3371	0.3490	57A	0.3215	0.3350	65A	0.3048	0.3207
	0.3615	0.3659		0.3451	0.3554		0.3290	0.3417		0.3130	0.3290
	0.3590	0.3521		0.3440	0.3427		0.3290	0.3300		0.3144	0.3186
	0.3512	0.3465		0.3366	0.3369		0.3222	0.3243		0.3068	0.3113
45B	0.3548	0.3736	50B	0.3376	0.3616	57B	0.3207	0.3462	65B	0.3028	0.3304
	0.3641	0.3804		0.3463	0.3687		0.3290	0.3538		0.3115	0.3391
	0.3615	0.3659		0.3451	0.3554		0.3290	0.3417		0.3130	0.3290
	0.3530	0.3597		0.3371	0.3490		0.3215	0.3350		0.3048	0.3207
45C	0.3641	0.3804	50C	0.3548	0.3736	57C	0.3207	0.3462	65C	0.3028	0.3304
	0.3736	0.3874		0.3463	0.3687		0.3290	0.3538		0.3115	0.3391
	0.3702	0.3722		0.3451	0.3554		0.3290	0.3417		0.3130	0.3290
	0.3615	0.3659		0.3371	0.3490		0.3215	0.3350		0.3048	0.3207
45D	0.3615	0.3659	50D	0.3451	0.3554	57D	0.3290	0.3417	65D	0.3130	0.3290
	0.3702	0.3722		0.3440	0.3427		0.3290	0.3300		0.3144	0.3186
	0.3670	0.3578		0.3366	0.3369		0.3222	0.3243		0.3068	0.3113
	0.3590	0.3521		0.3440	0.3428		0.3290	0.3300		0.3144	0.3186
			50R	0.3429	0.3307	57R	0.3290	0.3180	65R	0.3161	0.3059
				0.3361	0.3245		0.3231	0.3120		0.3093	0.2993
				0.3381	0.3762		0.3196	0.3602		0.3005	0.3415
				0.3480	0.3840		0.3290	0.3690		0.3099	0.3509

			0.3463	0.3687			0.3290	0.3538		0.3115	0.3391
			0.3376	0.3616			0.3207	0.3462		0.3028	0.3304
							0.3290	0.3690		0.3099	

57T

65T



1.6 Typical optical characteristics curves 典型光学特性曲线

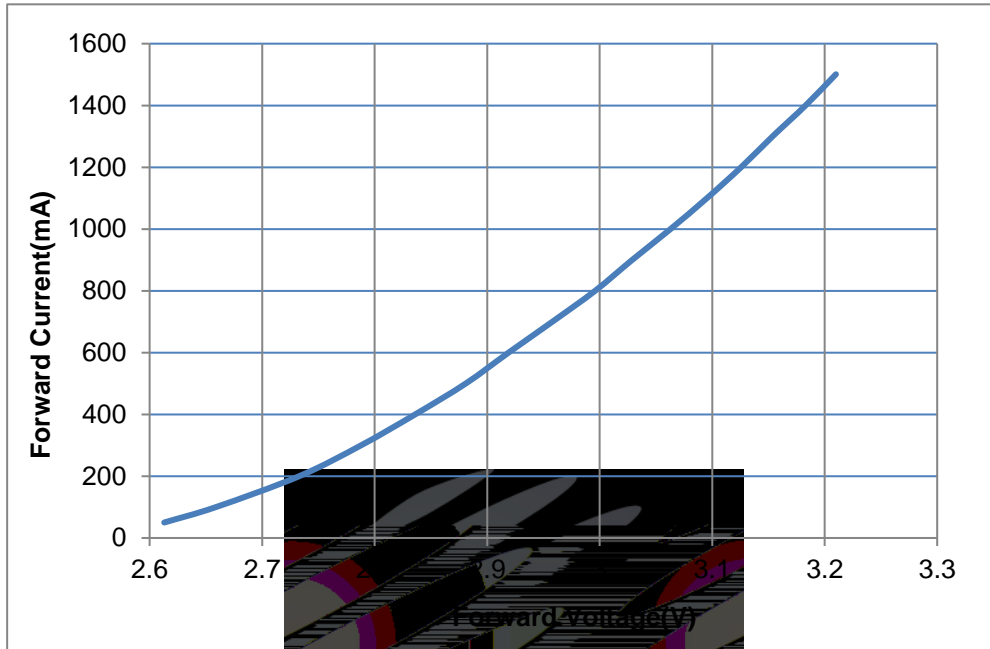


Fig 1-6 Forward Voltage Vs Forward Current (安特性曲线)

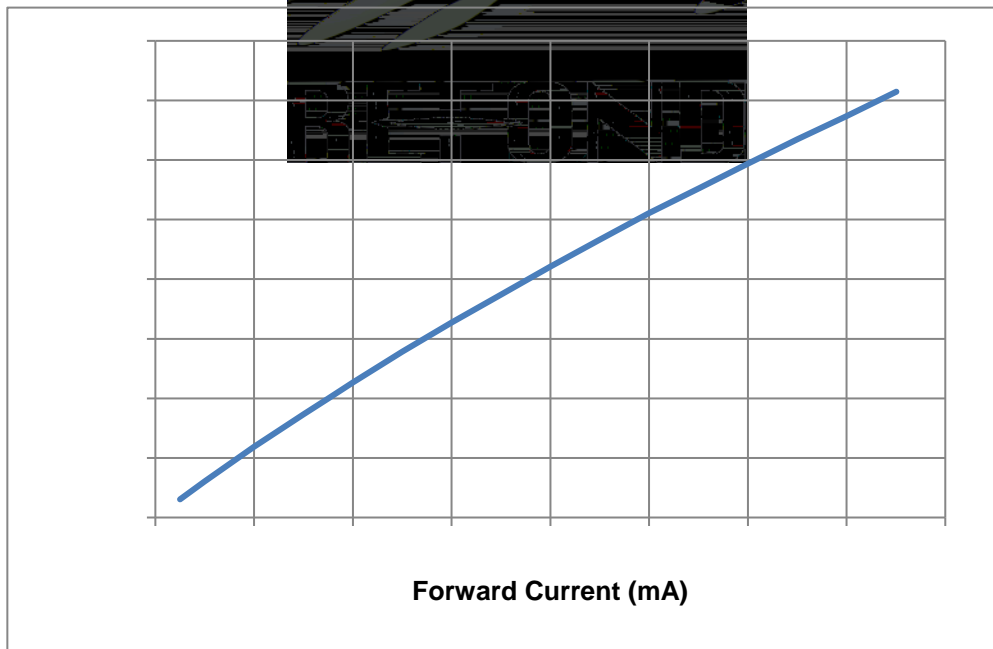


Fig.1-7 Forward Current Vs Relative Intensity

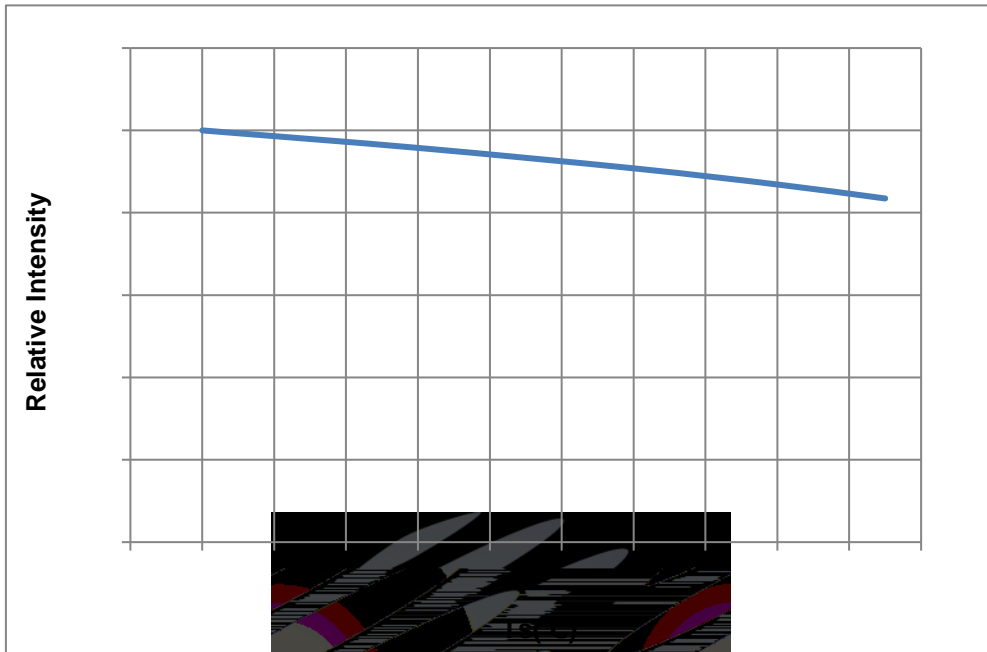


Fig.1-8 Temperature Vs Relative Intensity

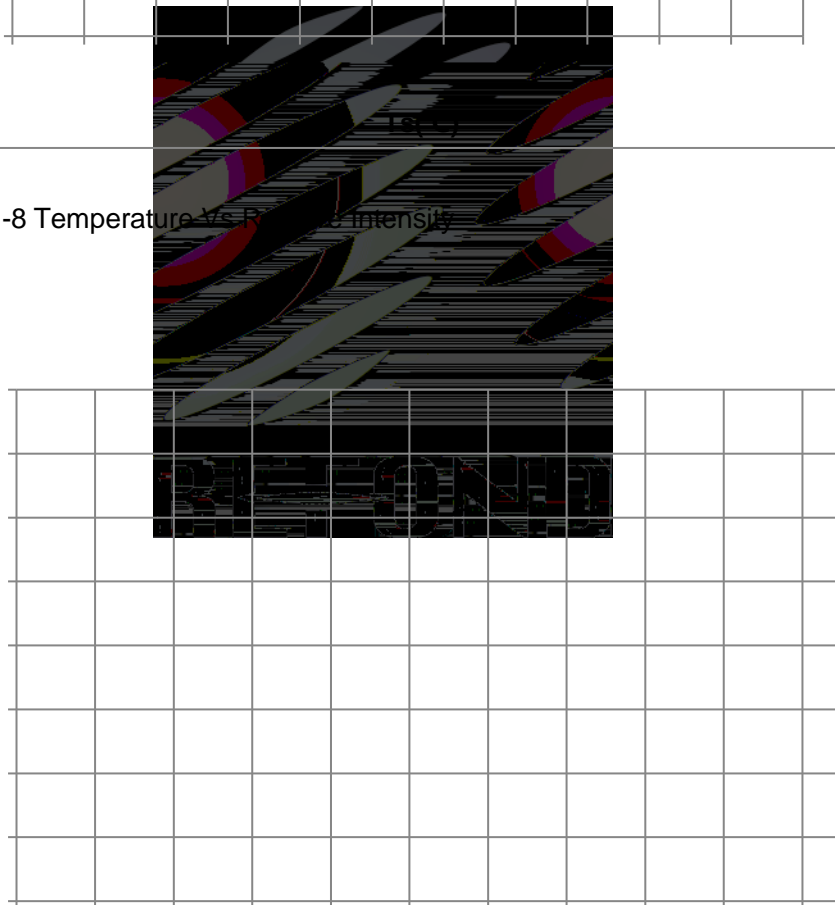
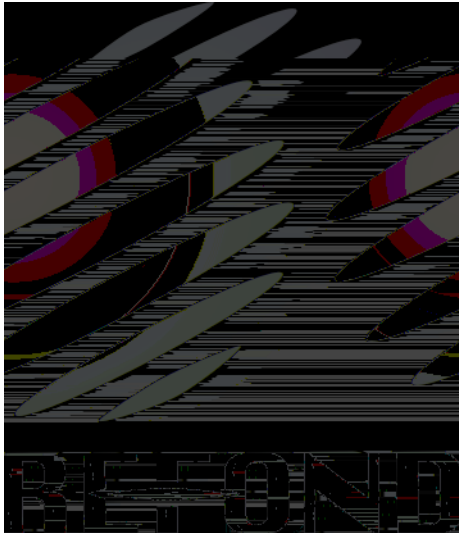


Fig 1-9 Ts Temperature Vs Forward Current 管脚温度与正向电流特性曲



2. Packaging 产品包装

2.1 Packaging Specification 包装规格

Package: 1000pcs/reel. 包装每卷

2.1.1 Carrier Tape Dimension 载带尺寸

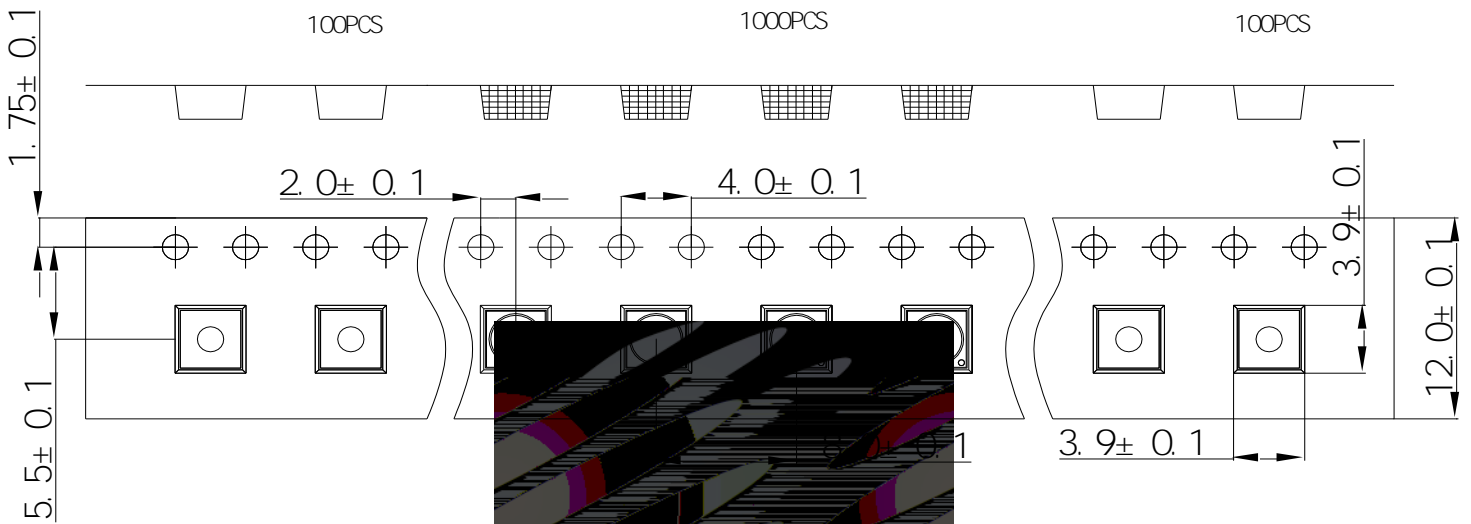


Fig.2-1 Carrier Tape Dimension 载带尺寸

2.1.2 Reel Dimension 卷盘尺寸

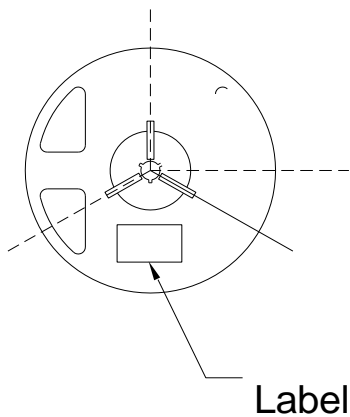


Fig.2-2 Reel 卷盘

Table 2-1 Reel Dimension 卷盘尺寸

A	14.0±0.5mm
B	178±1mm
C	59±1mm
D	13.9±0.5mm

Notes 备注:

The tolerances unless mentioned ± 0.1 mm. Unit : mm 注: 未注公差为 ± 0.1 毫米, 尺寸单位: 毫米。

2.1.3 Label Form Specification 标签规格

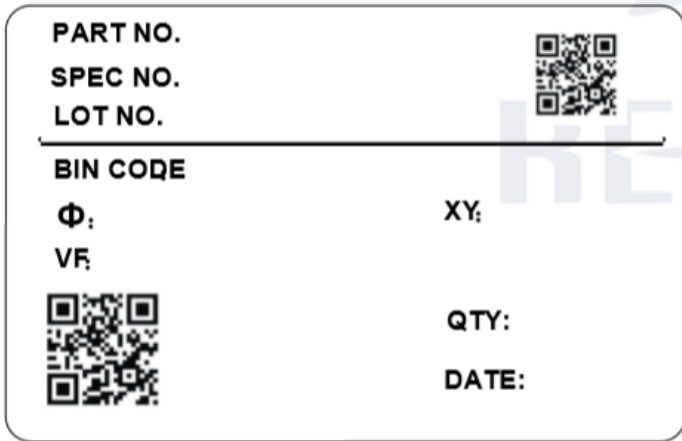
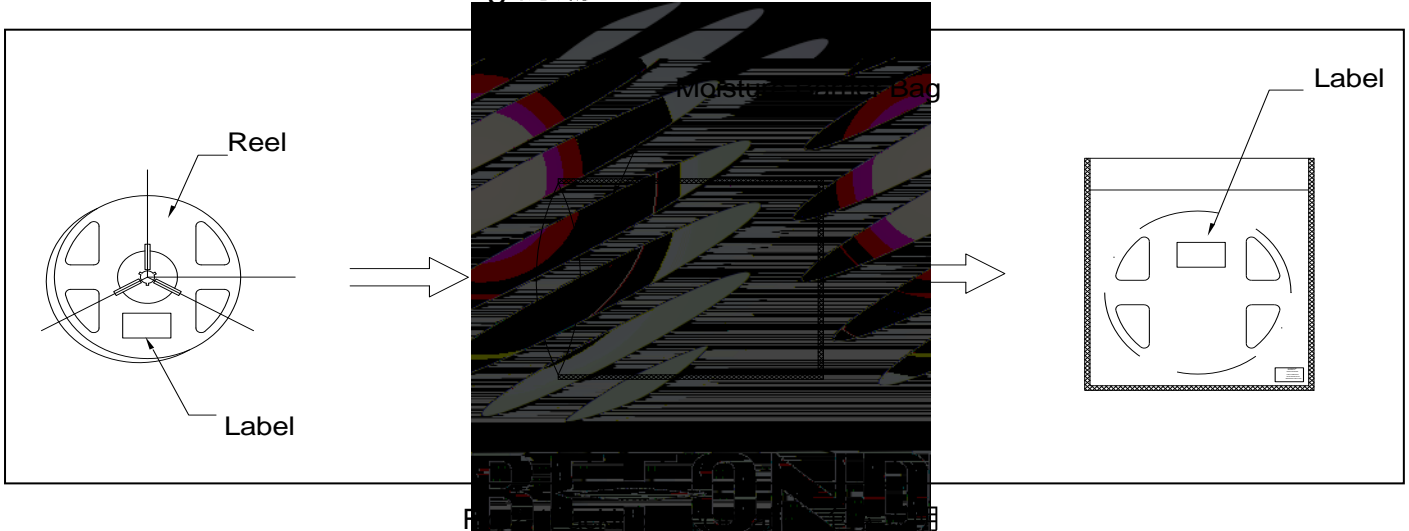


Fig 2-3 Label Form 标签模板

Table 2-2 Label Parameter 标签参数

PART NO.	Part Number 品名
SPEC NO.	Spec Number 规格
LOT NO.	Lot Number 批次号
BIN CODE	Bin Code 参数代码
	Luminous flux 光通量
XY	Chromaticity Bin 色区
V _F	Forward Voltage 正向电压
QTY	Packing Quantity 数量
DATE	Made Date 生产日期

2.2 Moisture Resistant Packing 防潮包装



2.3 Cardboard Box 包装纸箱

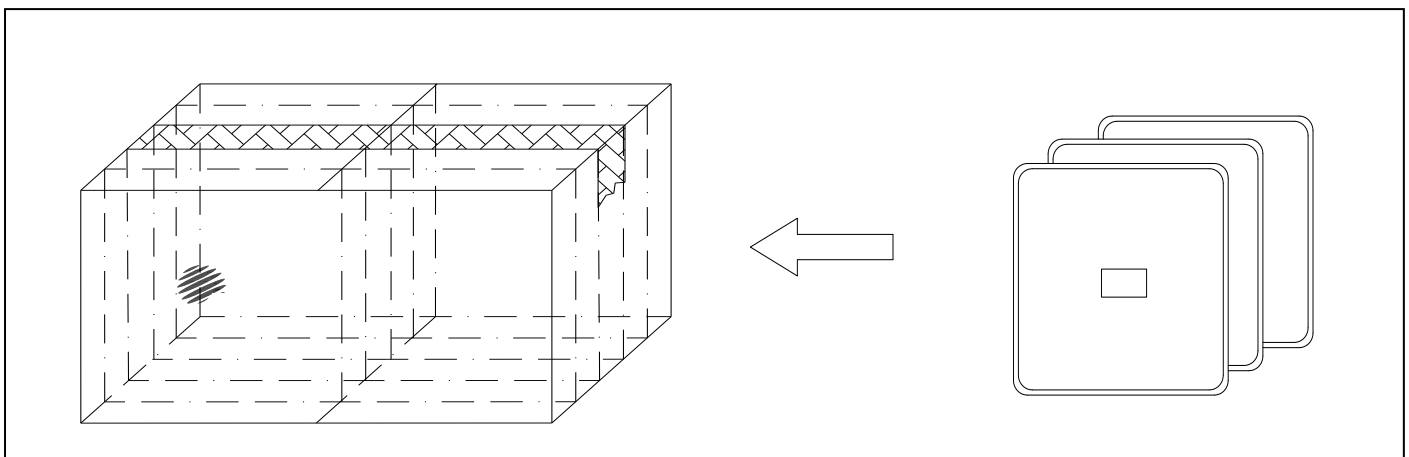
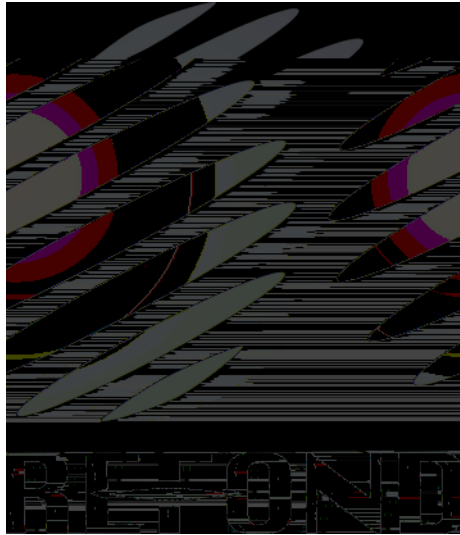


Fig.2-5 Cardboard Box 包装纸箱

2.4 Reliability Test Items And Conditions 信赖性测试项目及条件

Table 2-3 Test items and conditions 测试项目及条件

TestItems	Ref.Standard	Test Condition	Time	Quantity	Ac/Re
项目	参考标准	测试条件	时间	数量	接收/拒收



2.5 Criteria For Judging Damage 失效判定标准

Table 2-4 Criteria for judging damage 失效判定标准

Test Items 项目	Symbol 符号	Test Condition 测试条件	Criteria For Judgement 判定标准	Applicable project 适用项目
Forward Voltage 电压	V_F	$I_F=350mA$	$\leq \pm 10\%$	Reflow Thermal Shock
Luminous Flux W		$I_F=350mA$	Maintenance $\geq 80\%$ 光通量维持率	High and Low Temperature Storage
Lamp Bead Light Test 灯珠点亮测试	/		short circuit or flicker 短路、闪变	High Temperature High Humidity Life Test

Notes 备注:

1. The above reliability tests is based on the verification of a single/strip LED of Refond's existing experimental platform, the reliability experiment was conducted under the following conditions. when customers applies the LED to the series and parallel circuit, the factors such as the current, voltage distribution, heat dissipation and others. 以上可靠性测试是基于瑞丰现有实验平台单颗/条 LED 在良好散热条件验证下的结果。客户端将 LED 应用于串、并联线路时，需自行评估电流、电压分配、散热等问题。

2. The technical information shown in the data sheets is limited to the typical characteristics and circuit examples of the referenced products. It does not constitute the warranting of industrial property nor the granting of any license. 以上技术数据仅为产品的典型值，只作为参考，不作为任何应用条件及应用方式的保证。

3. SMT Reflow Soldering Instructions SMT 回流焊说明

3.1 SMT Reflow Soldering Instructions SMT 回流焊说明

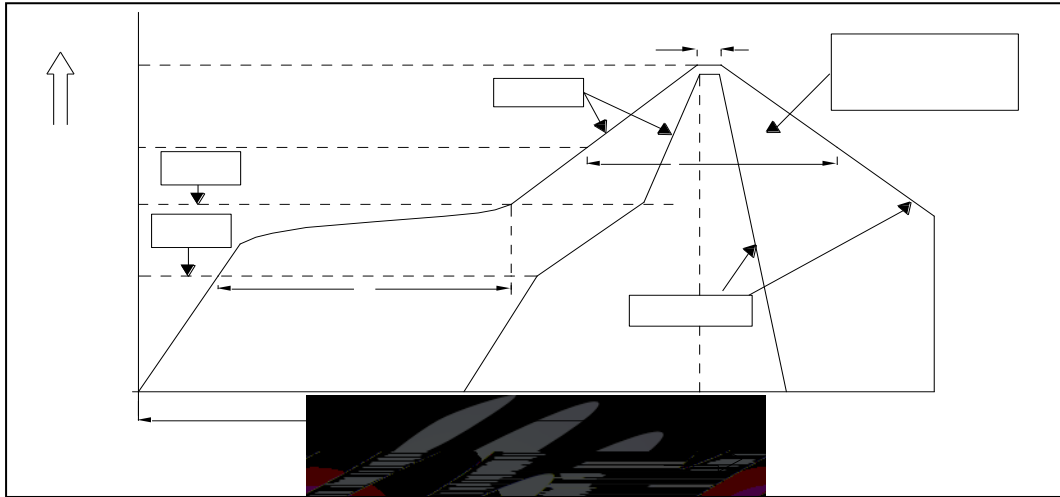
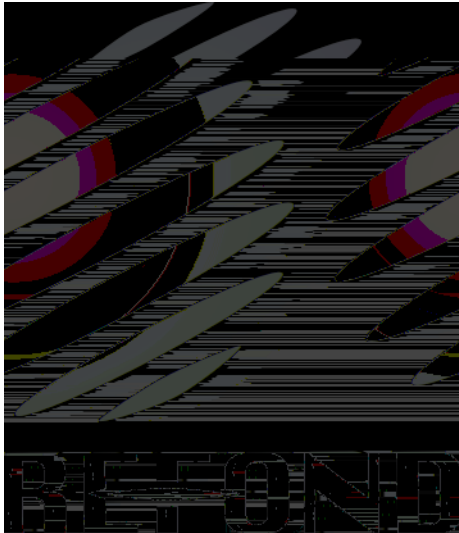


Fig.3-1 SMT Reflow Soldering Instructions SMT 回流焊说明

Table 3-1 SMT Reflow Soldering Parameter SMT 回流焊参数

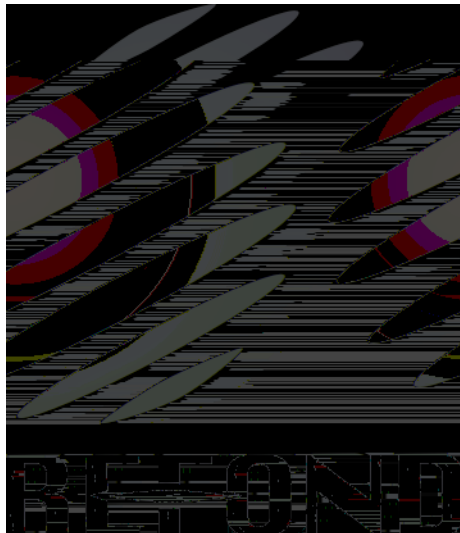
Average temperature rise speed 平均升温速度 (T _{max} 至 T _p)	Max 3 °C/ s 最高3 °C/秒
Preheating: minimum temperature 预热: 最低温度 (T _{min})	150 °C
Preheating: Max temperature 预热: 最高温度 (T _{max})	200 °C
Preheating: Time 预热: 时间 (T _{min} 至 T _{max})	60 - 120秒 60s-120s
Time limited to maintain high temperature: the temperature 限时维持高温: 温度 (T _L)	217 °C
Time limited to maintain high temperature: The Time 限时维持高温: 时间 (t _L)	Max 60s 最多60秒
Peak /Classification of temperature: 峰值 / 分类温度 (T _P)	260 °C
Time limit classification of peak temperature time 限时峰值分类温度: 时间 (t _p)	Max 10s 最多10秒



表面较软，用力按压胶体表面会影响LED可靠性，因此应有预防措施避免在按压器件，当使用吸嘴时，胶体表面的压力应是恰当的。

(2) Components should not be mounted on warped (non coplanar) portion of PCB. After soldering, do not warp the circuit board. LED 灯珠不要焊接在弯曲的 PCB 板上，焊接之后，也不要弯折电路板。

(3) Do not apply mechanical force or excess vibration during the cooling process to normal temperature after soldering. Do not rapidly cool device after soldering.回流焊之后冷却过程中，不要对材料施加外力，也不要震动，回流焊后，不要采用激剧冷却的方式。



4. Handling Precautions 产品使用注意事项

4.1 Handling Precautions 产品使用注意事项

(1) LED operating environment and sulfur element composition cannot be over 100PPM in the LED mating usage material. This is provided for informational purposes only and is not a warranty or endorsement. LED 工作环境及与 LED 适配的材料中硫元素及化合物成份不可超过 100PPM. 这只是一个建议，不作任何品质担保。

(2) In order to prevent external material from getting into the inside of LED, which may cause the malfunction of LED, the single content of Bromine element is required to be less than

900PPM, the single content of Chlorine element is required to be less than 900PPM, the total content of Bromine element and

products is required to be less than 1500PPM. This is provided for informational purposes only and is not a warranty or endorsement. 为防止外界物质进入 LED 内部以造成 LED 的损伤，所处环境及所用套件等等，单一的溴元素含量要求小于 900PPM，单一氯元素含量要求小于 900PPM，溴元素与氯元素总含量必须小于 1500PPM. 这只是一个建议，不作任何品质担保。

(3) VOCs (Volatile organic compounds) emitted from materials used in the construction of fixtures can penetrate silicone encapsulants of LEDs and discolor when exposed to heat and photonic energy. The result can be a significant loss of light output from the fixture. Knowledge of the properties of the materials selected for the construction of fixtures can help prevent these issues. Refond advises against the use of any chemicals or materials that have been found or are suspected to have an adverse affect on device performance or reliability. To

verify compatibility, Refond recommends that all chemicals and materials be tested in the specific application and environment for which they are intended to be used. Attaching LEDs, do not use adhesives that outgas organic vapor. LED 内部，在通电产生光子及热的条件下，会导致 LED 变色，进而造成严重光衰，提前了解套件材料能够避免产生这些问题。

瑞丰反对使用任何对 LED 器件的性能或者可靠性有害的物质或材料，不管这些材料是已经证实了的还是仅仅怀疑有害。针对特定的用途和使用环境，瑞士建议对所有的物质和材料进行相容性的测试。在贴装 LED 时候，不要使用能产生有机挥发性气体的粘结剂。

(4) Handle the component along the side surface by using forceps or appropriate tools; do not directly touch or Handle the silicone lens surface, it may damage the internal circuitry. 通过使用适当的工具从材料侧面夹取，不可直接用手或尖锐金属压胶体表面，它可能会损坏内部电路。

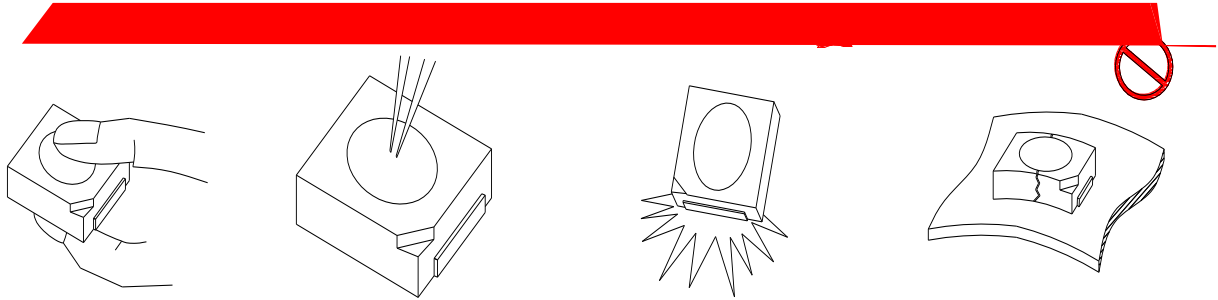


Fig 4-1 Misoperation 错误操作

(5) In designing a circuit, the current through each LED must not exceed the absolute maximum rating specified for each LED. In the meantime, resistance protection should be applied, otherwise slight voltage shift will cause big current change, burn out may happen. The driving circuit must be designed to allow forward voltage only when it is ON or OFF. If the reverse voltage is applied to LED, migration may be generated resulting in LED damage. 设计电路时，通过 LED 的电流不能超过规定的额定值，同时要加电阻保护，否则，微小的电压变化将会引起很大的电流变化，不能保证产品的使用寿命。不要施加反压，否则会损坏 LED。

(6) Thermal Design is paramount importance because heat generation may result in the Characteristics decline, such as brightness decreased, Color change and so on. Please consider the heat generation of the LEDs when making the system design. LED 容易因为自身的发热和环境温度的改变而改变，温度升高会降低 LED 发光效率，影响发光颜色，所以在设计时应充分考虑散热问题。

(7) Compared to standard encapsulants, silicone is generally softer, and the surface is more likely to attract dust · requiring special care during processing. In cases where a minimal level of dirt and dust particles cannot be guaranteed, a suitable cleaning solution must be applied to the surface after the soldering of components. Refond suggests using isopropyl alcohol for cleaning. In case other solvents are used, it must be assured that these solvents do not dissolve the package or resin. Ultrasonic cleaning is not recommended. Ultrasonic cleaning may cause

damage to the LED. 与其他封装胶相比，硅胶通常较软，表面易吸附脏物，应用时应特别注意。当对产品洁净度要求较高时，回流焊以后需要采用恰当清洗方式，我们推荐使用异丙醇作清洗剂。如需要用到其他清洗剂，必须保证不会破坏封装体，超声清洗可能会对 LED 带来损害，不推荐这种清洗方式。

Table 4-1 Storage 储存

Conditions 种类		Temperature	Humidity 湿度	Time 时间
Storage	Before Opening Aluminum Bag 拆包前	30°C	75%	Within 6 Months From Date 6个月内
	After Opening Aluminum Bag 拆包后	25°C	60%	168hours 168小时
Baking 烘烤		60±5°C	5%	≥24hours 大于24小时

(8) If the moisture absorbent material in the package or the LEDs have exceeded the storage time, baking treatment is required. The baking temperature is 60±5°C and based on the following condition (60±5) and less than 5%RH for above 24 hours. 如果干燥剂或包装失效，或者产品不符合以上有效储存条件，需拆包后进行烘烤。烘烤条件：60±5°C，小于5%RH，大于24小时。

If the package is flatulence or damaged, please notify the sales staff to assist. 如果包装胀气或者破损，请及时与销售工程师联系。

(9) Similar to most Solid state devices; LEDs are sensitive to Electro-Static Discharge (ESD) and Electrical Over Stress (EOS). 像其他的半导体电子器件一样，LED 对静电过流击穿非常敏感，需要做好防护。

(10) Other points for attention, please refer to our relevant information. 其它注意事项请参照瑞丰相关产品资料。

Date日期	Revisor修订者	Version版本	Verifier审核	Remarks备注
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